



UST070SSMNCE00

7.0" IPS LCD-TFT MODULE SPECIFICATION

Key Specifications

Parameter	Specification
LCD Type	IPS TFT / Transmissive / Normal Black
Size (Diagonal)	7.0"
Viewing Direction	Full Viewing (All)
Outside Dimensions (W x H x D)	165.10 x 100.10 x 7.81 mm
Active Area (W x H)	154.21 x 85.92 mm
Pixel Pitch (W x H)	0.1506 x 0.1432 mm
Resolution	1024 x 600 (RGB)
Brightness	900 cd / m ² (typ.)
Contrast Ratio	1000:1 (typ.)
Color Depth	16.7 M
Pixel Arrangement	RGB Vertical Stripe
Interface	MIPI DSI
LCD Driver	JD9165BA
With / Without Touch	With Capacitive Touch (CTP)
CTP Driver	ILI2520 (USB / I2C)
Surface Treatment	Glare
Operating / Storage Temp.	-20°C ~ +70°C / -30°C ~ +80°C
Weight	210 g

Revision Table

Rev.	Date	Description
1.0	2026-10-06	First issue
1.1	2026-10-07	Minor updates
1.2	2026-10-13	Improvement of the chapter layout

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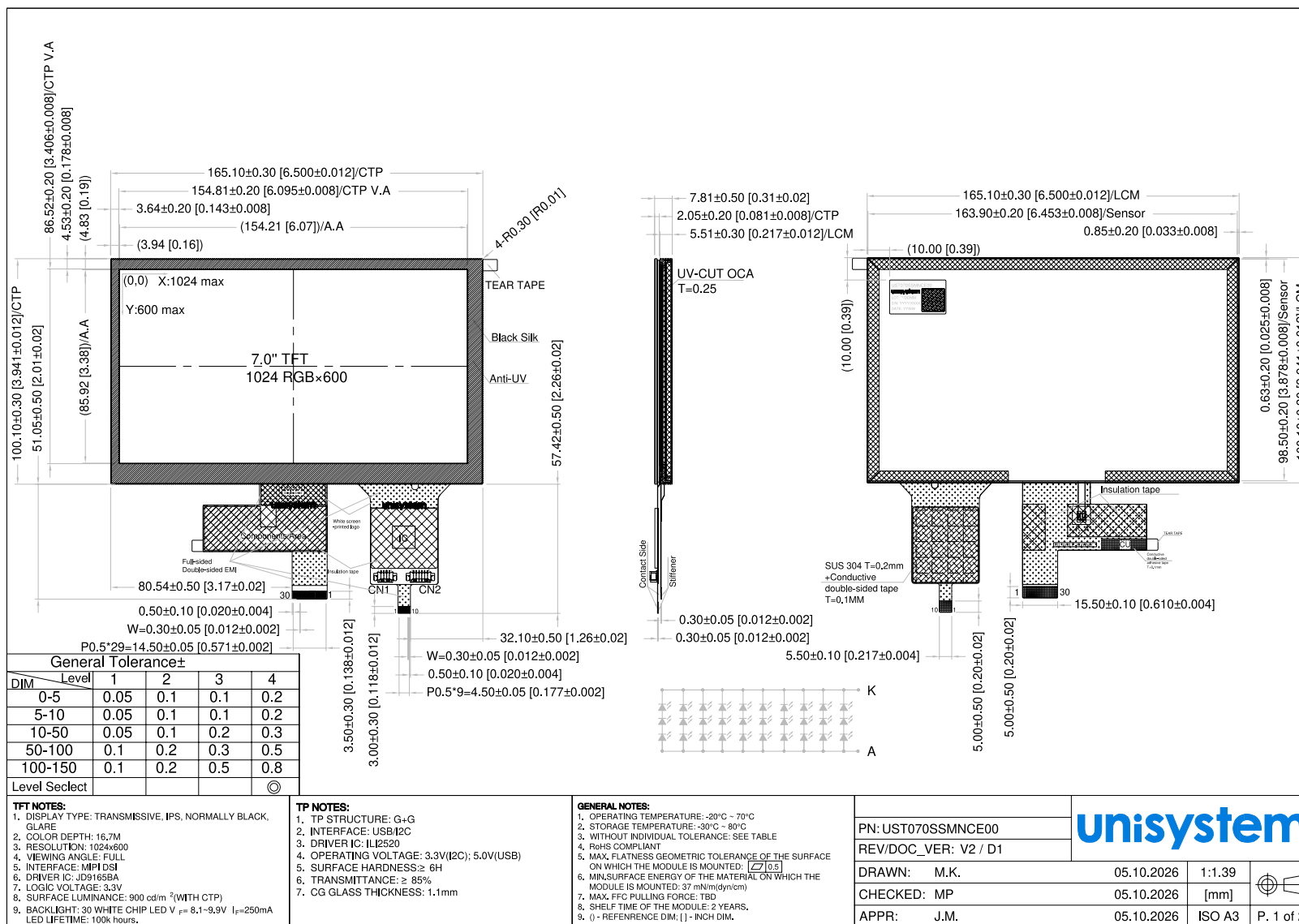
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1. Coding System

1	2	3	4	5	6	7	8	9	10
US	T	070	S	S	M	N	C	E	00

No.	Parameter	Options
1	Manufacturer	Unisystem
2	Display Type	T – TFT
3	Display Size	070 – 7", 101 – 10.1", 121 – 12.1", 156 – 15.6"
4	Model Series	S – “Core” Standard Brightness IPS, H – “Pro” High Brightness IPS, L – “Lite” IPS
5	Resolution	M – 800x480, S – 1024x600 (WSVGA), W – 1280x800 (WXGA), X – 1024x768 (XGA), F – 1920x1080 (FHD)
6	Interface	L – LVDS, M – MIPI DSI, R – RGB, D – eDP, H – HDMI and USB-C
7	Frame	F – With Mounting Metal Frame, N – Without Mounting Metal Frame
8	Touch Panel	N – Without Touch Panel, C – With Projected Capacitive Touch Panel
9	Cover Glass Specification	N – Without Cover Glass, E – Rectangular Glass with Optical Bonding, U – Rounded Glass with Optical Bonding
10	Version	00 – base series, 10 – improved series

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3. Absolute Maximum Ratings

Item	Symbol	Min.	Max.	Unit
Power supply voltage	V_{DD}	-0.3	3.96	V
Storage temperature	T_{STG}	-30	+80	°C
Operating temperature	T_{OP}	-20	+70	°C

$V_{SS} = 0V$, $T_a = 25^{\circ}C$

Note 1: If T_a is below $50^{\circ}C$, the maximum humidity is 90%RH; if T_a is over $50^{\circ}C$, the absolute humidity shall not exceed that of 60%RH at $50^{\circ}C$.

Note 2: The response time will be extremely slow when the operating temperature is around $-10^{\circ}C$ or below, and the background will become darker during high-temperature operation.

4. DC Characteristics

Item	Symbol	Min.	Typ.	Max.	Unit
Supply Voltage	V_{DD}	2.8	3.3	3.6	V
Logic-High Input Voltage	V_{ih}	$0.8 \times V_{DD}$	-	V_{DD}	V
Logic-Low Input Voltage	V_{il}	GND	-	$0.2 \times V_{DD}$	V
Logic-High Output Voltage	V_{oh}	$0.9 \times V_{DD}$	-	V_{DD}	V
Logic-Low Output Voltage	V_{ol}	GND	-	$0.1 \times V_{DD}$	V
Current Consumption (All white)	I_{DD}	-	136	-	mA

5. Backlight Characteristics

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$T_a = 25^{\circ}C$, $I_F = 25mA$ / LED	8.1	9.3	9.9	V
Forward Current	I_F	$T_a = 25^{\circ}C$, $I_F = 25mA$ / LED	-	250	-	mA
Power Dissipation	P_D	-	-	2325	-	mW
Uniformity	Avg	-	-	80	-	%
LED working life ($25^{\circ}C$)	-	-	-	100,000	-	Hrs
Drive method	Constant current					
LED Configuration	30 White LEDs (3 LEDs in one string and 10 groups in parallel)					

Note 1: LED lifetime is defined as the time until the brightness drops to 50% of its initial value.

The test is conducted under ambient air flow, at $T_a = 25 \pm 2^{\circ}C$, 60%RH $\pm 5\%$, $I_F = 25mA$ / LED.

6. Touch Screen Panel Specifications

Item	CTP Description	
1	IC	ILI2520
2	Interface	USB / IIC
3	Operating voltage	5V / 3.3V
4	Interface signal voltage	3.3V / 3.3V
5	Surface hardness	≥ 6H
6	Operating temperature	-20°C ~ +70°C
7	Storage temperature	-30°C ~ +80°C
8	Strengthened Type	Chemical
9	Transmittance	≥ 85%
10	Origin of coordinates	Top Left
11	Resolution	1024 x 600

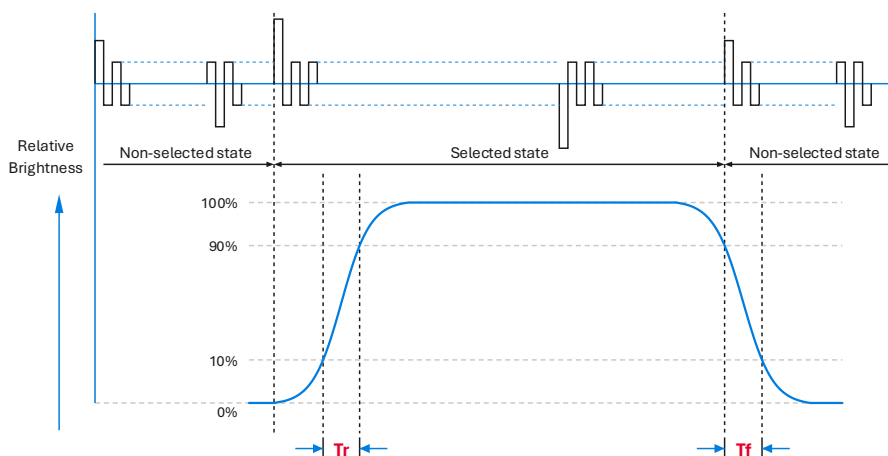
7. Optical Characteristics

Ta = 25°C, V_{DD} = 3.3V

Backlight On (Transmissive Mode)	Item		Symbol	Condition	Specification			Unit
					Min.	Typ.	Max.	
	Luminance with CTP (I _F = 25mA / LED)		L _V		-	900	-	cd / m ²
	Contrast ratio (See 7.2)		CR		700	1000	-	
	Response time (See 7.1)		T _R + T _F		-	30	35	ms
	Chromaticity Transmissive (See 7.4)	Red	X _R		0.550	0.600	0.650	
			Y _R		0.326	0.376	0.426	
		Green	X _G		0.283	0.333	0.383	
			Y _G		0.518	0.568	0.618	
		Blue	X _B		0.084	0.134	0.184	
			Y _B		0.038	0.088	0.138	
		White	X _W		0.261	0.311	0.361	
			Y _W		0.301	0.351	0.401	
	Viewing Angle (See 7.3)	Horizontal	θ _{X+}	Center CR ≥ 10	70	80	-	Deg.
			θ _{X-}		70	80	-	
		Vertical	φ _{Y+}		70	80	-	
φ _{Y-}			70		80	-		
NTSC Ratio (Gamut)				45	50	-	%	

7.1 Definition of Response Time

7.1.1 Normally Black Type (Negative)

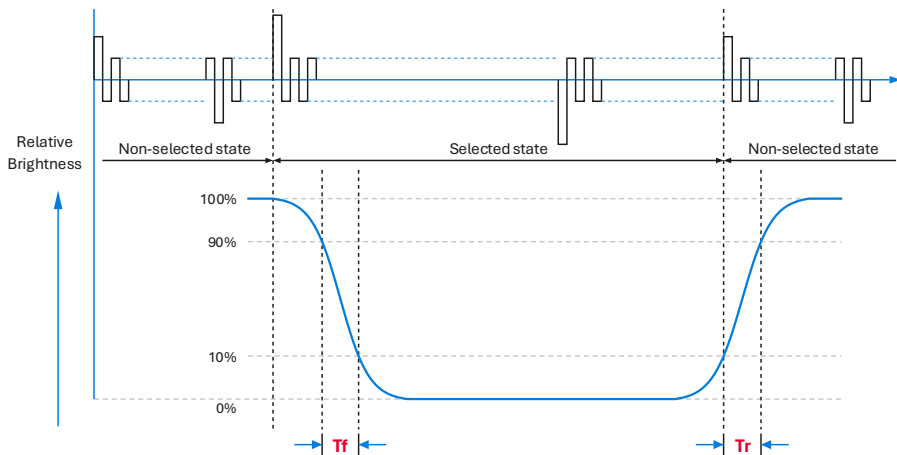


Tr is the time it takes to change from non-selected state with relative luminance 10% to selected state with relative luminance 90%.

Tf is the time it takes to change from selected state with relative luminance 90% to non-selected state with relative luminance 10%.

Note: Measuring machine: LCD-5100

7.1.2 Normally White Type (Positive)



Tr is the time it takes to change from non-selected state with relative luminance 90% to selected state with relative luminance 10%.

Tf is the time it takes to change from selected state with relative luminance 10% to non-selected state with relative luminance 90%.

Note: Measuring machine: LCD-5100 or equivalent

7.2 Definition of Contrast Ratio

Contrast is measured perpendicularly to the display surface in transmissive mode.

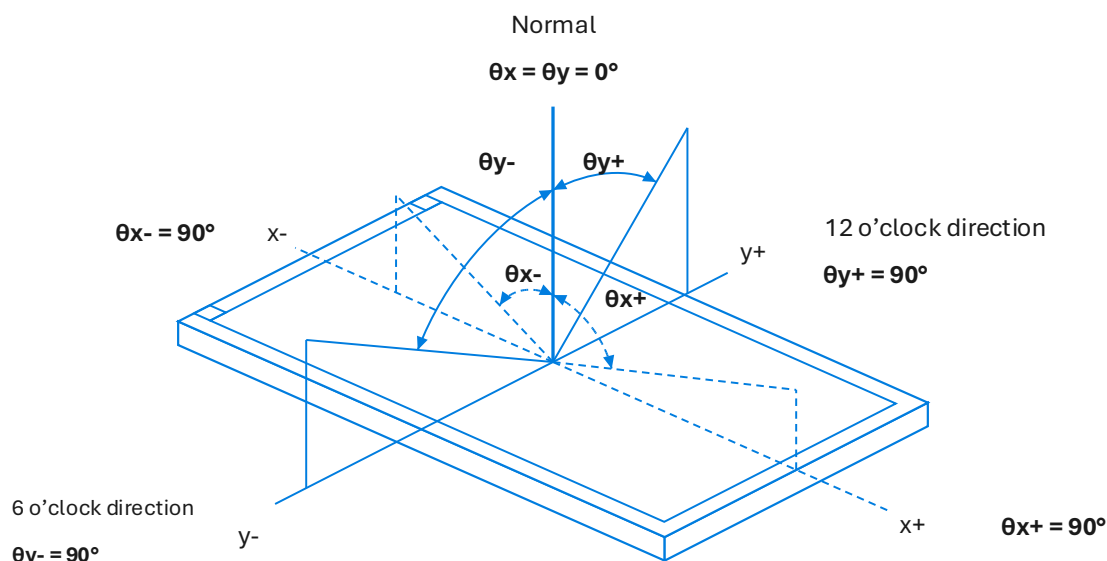
The measurement condition is:

Measuring Equipment	Eldim or equivalent
Measuring Point Diameter	3mm / 1mm
Measuring Point Location	Active Area center point
Test pattern	A: All pixels white
	B: All pixels black
Contrast setting	Maximum

Definition: CR (Contrast) = Luminance of White Pixel / Luminance of Black Pixel

7.3 Definition of Viewing Angles

Measuring machine: LCD-5100 or equivalent

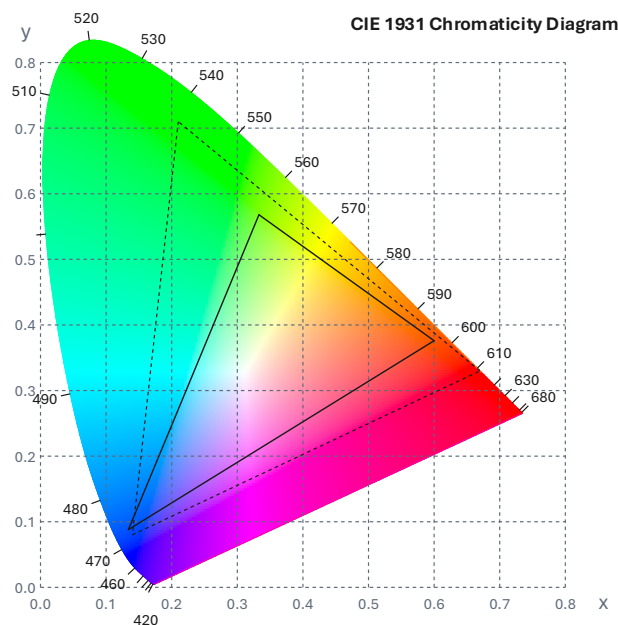


7.4 Definition of Color Appearance

R, G, B and W are defined by (x, y) coordinates on the CIE chromaticity diagram.

NTSC = area of RGB triangle / area of NTSC triangle x 100%

Measuring picture: Red, Green, Blue and White (Measuring machine: BM-7)



7.5 Definition of Surface Luminance, Uniformity and Transmittance

Using the transmissive mode measurement approach, measure the white screen luminance of the display panel and backlight.

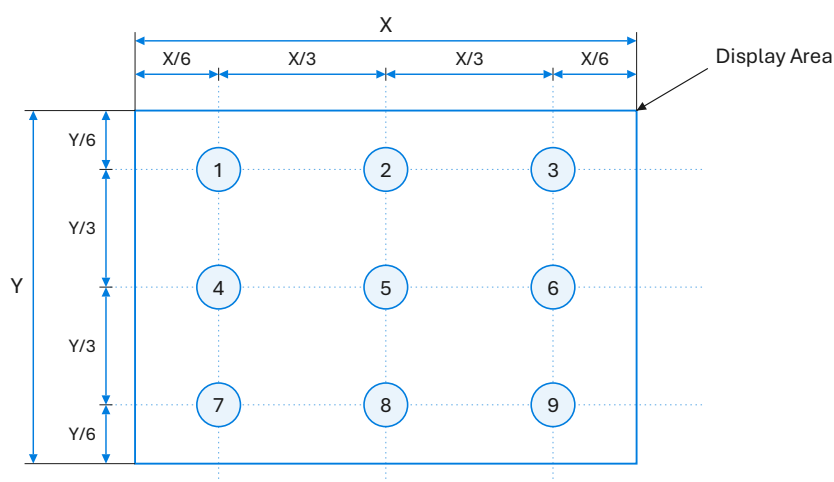
Surface Luminance: $L_V = \text{average } (L_{P1}:L_{P9})$

Uniformity = $\text{Minimum } (L_{P1}:L_{P9}) / \text{Maximum } (L_{P1}:L_{P9}) \times 100\%$

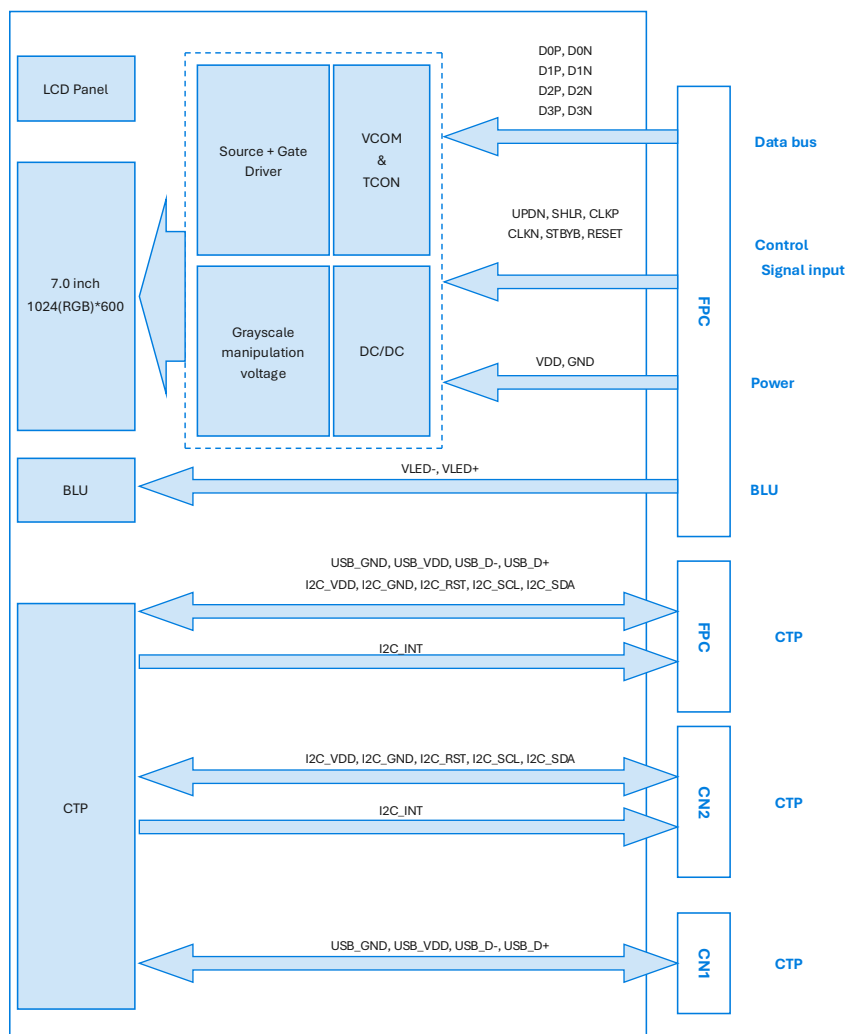
Transmittance = $L_V \text{ on LCD} / L_V \text{ on Backlight} \times 100\%$

Note: Measuring machine: BM-7

Note: Test 3 brightness points below 3.5 inches (point 2 / 5 / 8), test 5 brightness points between 3.5–7 inches (point 1 / 3 / 5 / 7 / 9), and test 9 brightness points above 7 inches (point 1 to 9).



8. Block Diagram and Power Supply



9. Interface Pins Definition

No.	Symbol	Function
1-2	VLED+	LED Anode.
3-4	NC	No connection
5	UPDN	Vertical inversion ¹⁾
6	SHLR	Horizontal inversion ²⁾
7-8	VLED-	LED Cathode.
9	NC	No connection
10	GND	Ground
11	D3P	MIPI data Input positive-end
12	D3N	MIPI data Input negative-end

No.	Symbol	Function
13	GND	Ground
14	D2P	MIPI data Input positive-end
15	D2N	MIPI data Input negative-end
16	GND	Ground
17	CLKP	MIPI clock Input positive-end
18	CLKN	MIPI clock Input negative-end
19	GND	Ground
20	D1P	MIPI data Input positive-end
21	D1N	MIPI data Input negative-end
22	GND	Ground
23	D0P	MIPI data Input positive-end
24	D0N	MIPI data Input negative-end
25	GND	Ground
26	STBYB	Dummy – connect to V _{DD}
27	RESET	Reset signal, active low
28-29	V _{DD}	Power supply
30	NC	No connection

Note

1) Vertical inversion (Default pull Low)

UPDN	Function
1	Bottom → Top
0	Top → Bottom

2) Horizontal inversion (Default pull Low)

SHLR	Function
1	Right → Left
0	Left → Right

CTP PIN:

No.	Symbol	Function
1	USB_GND	Ground
2	USB_VDD	Power Supply
3	USB_D-	Data-
4	USB_D+	Data+
5	I2C_GND	CTP Ground
6	I2C_VDD	CTP Power Supply
7	I2C_RST	CTP Reset input signal, active low
8	I2C_SCL	CTP Clock input signal
9	I2C_INT	CTP Interrupt output signal
10	I2C_SDA	CTP Data input / output signal

CN1 PIN:

No.	Symbol	Function
1	USB_VDD	Power Supply
2	USB_D-	Data-
3	USB_D+	Data+
4	USB_GND	Ground

CN2 PIN:

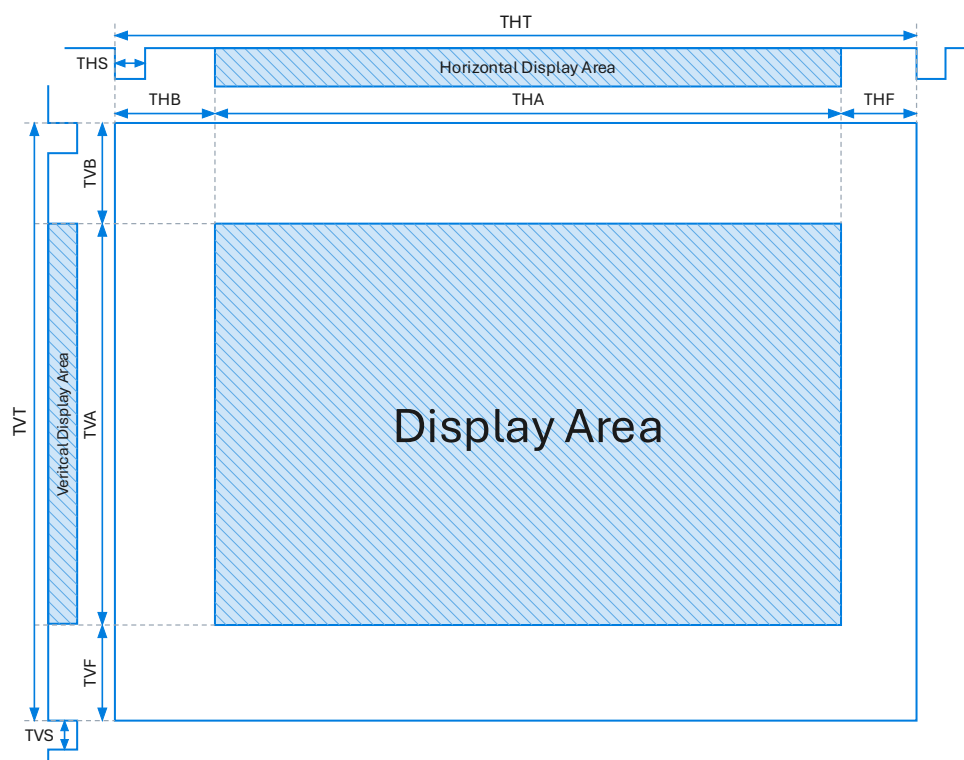
No.	Symbol	Function
1	I2C_GND	CTP Ground
2	I2C_VDD	CTP Power Supply
3	I2C_RST	CTP Reset input signal, active low
4	I2C_SCL	CTP Clock input signal
5	I2C_INT	CTP Interrupt output signal
6	I2C_SDA	CTP Data input / output signal

10. Timing Characteristics

10.1 MIPI Input Timing Table

MIPI Input Timing	Symbol	1024RGBX600			Unit
		Min.	Typ.	Max.	
MIPI 24-bit RGB @ 2 lane Operating Frequency	-	400	616	750	Mbps
MIPI 24-bit RGB @ 4 lane Operating Frequency	-	200	308	500	Mbps
Frame Rate @ 2 lane	-	48	60	-	Hz
Frame Rate @ 4 lane	-	48	60	-	Hz
Horizontal Total	t_{ht}	1114	1344	1400	DCLK
Hsync Pulse width	t_{hs}	1	24	HBP-1	DCLK
Horizontal Back Porch	t_{hb}	60	160	160	DCLK
Horizontal Valid Data	t_{hd}	1024			DCLK
Horizontal Front Porch	t_{hfp}	30	160	216	DCLK
Vertical Total	t_{vt}	620	635	800	THT
Vsync Pulse width	t_{vs}	1	2	VBP-1	THT
Vertical Back Porch	t_{vb}	8	23	100	THT
Vertical Valid Data	t_{vd}	600			THT
Vertical Front Porch	t_{vfp}	12	12	100	THT

10.2 MIPI Video Input Timing

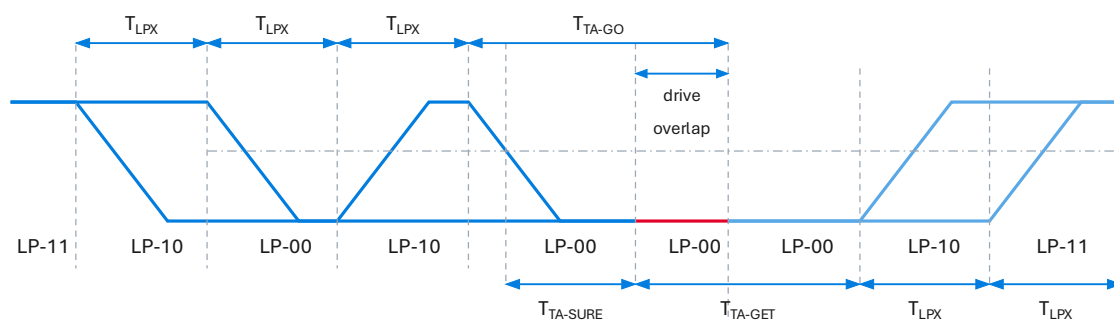


10.3 MIPI Low Power Transmitter AC Specification

Parameter		Symbol	Min.	Typ.	Max.	Units	Notes
15% ~ 85% rising time and falling time		T _{RLP} / T _{FLP}	-	-	25	ns	-
30% ~ 85% rising time and falling time		T _{REOT}	-	-	35	ns	-
Pulse width of LP exclusive-OR clock	First LP EXOR clock pulse after STOP state or Last pulse before stop state	T _{LP-PULSE-TX}	100	-	-	ns	-
	All other pulses		100	-	-	ns	
Period of the LP EXOR clock (LP Speed)		T _{LP-PER-TX}	200	-	-	ns	-
Slew Rate @ CLOAD = 0pF		δV / δt _{SR}	20	-	500	mV / ns	-
Slew Rate @ CLOAD = 5pF			20	-	200	mV / ns	-
Slew Rate @ CLOAD = 20pF			20	-	150	mV / ns	-
Slew Rate @ CLOAD = 70pF			20	-	100	mV / ns	-
Load Capacitance		C _{LOAD}	-	-	70	pF	-



Parameter	Symbol	Min.	Typ.	Max.	Units
Length of any Low-Power state period	T _{LPX}	100	-	-	ns
Time-out before new TX side start driving	T _{TA-Sure}	T _{LPX}	-	2T _{LPX}	ns
Time to drive LP-00 by new TX	T _{TA-GET}	-	5T _{LPX}	-	ns
Time to drive LP-00 after Turnaround Request	T _{TA-GO}	-	4T _{LPX}	-	ns



10.5 MIPI High Speed AC Characteristics

Parameter	Description	Spec.			Unit
		Min.	Typ.	Max.	
T_{REOT}	30%-85% rise time and fall time	-	-	35	ns
$T_{CLK-MISS}$	Timeout for receiver to detect absence of Clock transitions and disable the Clock Lane HS-RX.	-	-	60	ns
$T_{CLK-POST}^{*1}$	Time that the transmitter continues to send HS clock after the last associated Data Lane has transitioned to LP Mode. Interval is defined as the period from the end of $T_{HS-TRAIL}$ to the beginning of $T_{CLK-TRAIL}$.	$60\text{ ns} + 52 \cdot UI$	-		ns
$T_{CLK-PRE}$	Time that the HS clock shall be driven by the transmitter prior to any associated Data Lane beginning the transition from LP to HS mode.	8	-		UI
$T_{CLK-SETTLE}$	Time interval during which the HS receiver shall ignore any Clock Lane HS transitions, starting from the beginning of $T_{CLK-PRE}$.	95	-	300	ns
$T_{CLK-TERM-EN}$	Time for the Clock Lane receiver to enable the HS line termination, starting from the time point when Dn crosses $V_{IL,MAX}$.	Time for Dn to reach VTERM-EN	-	38	ns
$T_{HS-SETTLE}$	Time interval during which the HS receiver shall ignore any Data Lane HS transitions, starting from the beginning of $T_{HSPREPRE}$.	$85\text{ ns} + 6 \cdot UI$	-	$145\text{ ns} + 10 \cdot UI$	ns
T_{EOT}	Time from start of $T_{HS-TRAIL}$ or $T_{CLK-TRAIL}$ period to start of LP-11 state	-	-	$105\text{ ns} + n \cdot 12 \cdot UI$	-
$T_{HS-EXIT}$	Time to drive LP-11 after HS burst	100	-	-	ns
$T_{HS-PREPRE}$	Time to drive LP-00 to prepare for HS transmission	$40\text{ ns} + 4 \cdot UI$	-	$85\text{ ns} + 6 \cdot UI$	ns
$T_{HS-PREPRE} + T_{HS-ZERO}$	$T_{HS-PREPRE}$ + Time to drive HS-0 before the Sync sequence	$145\text{ ns} + 10 \cdot UI$	-	-	ns
$T_{HS-SKIP}$	Time-out at RX to ignore transition period of EoT	40	-	$55\text{ ns} + 4 \cdot UI$	ns
$T_{HS-TRAIL}$	Time to drive flipped differential state after last payload data bit of an HS transmission burst	$60\text{ ns} + 4 \cdot UI$	-	-	ns
T_{LPX}	Length of any Low-Power state period	100	-	-	ns
Ratio T_{LPX}	Ratio of $T_{LPX} \text{ (MASTER)} / T_{LPS} \text{ (SLAVE)}$ between Master and Slave side	2 / 3	-	3 / 2	-
T_{TA-GET}	Time to drive LP-00 by new TX	$5 \cdot T_{LPX}$			ns
T_{TA-GO}	Time to drive LP-00 after Turnaround Request	$4 \cdot T_{LPX}$			ns
$T_{TA-SURE}$	Time-out before new TX side starts driving	T_{LPX}	-	$2 \cdot T_{LPX}$	ns

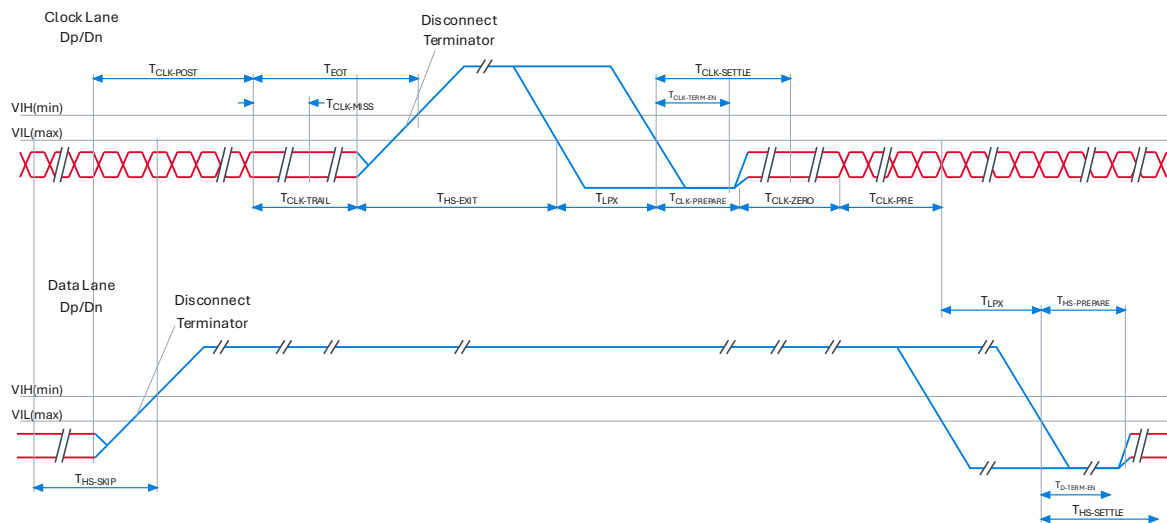
Note: (1) For $T_{CLK-POST}$ example:

$T_{CLK-POST}$ min value = 82UI when MIPI max frequency per lane = 0.5Gbps.

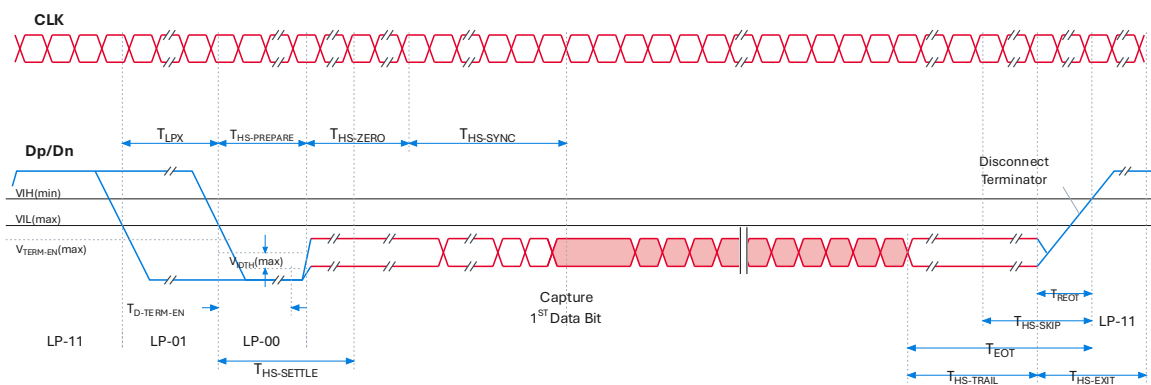
$T_{CLK-POST}$ min value = 112UI when MIPI max frequency per lane = 1Gbps

(2) For T_{EOT} :

When $n = 1$ for Forward-direction HS mode and $n = 4$ for Reverse-direction HS mode.



Switching the clock lane between clock transmission and low-power mode

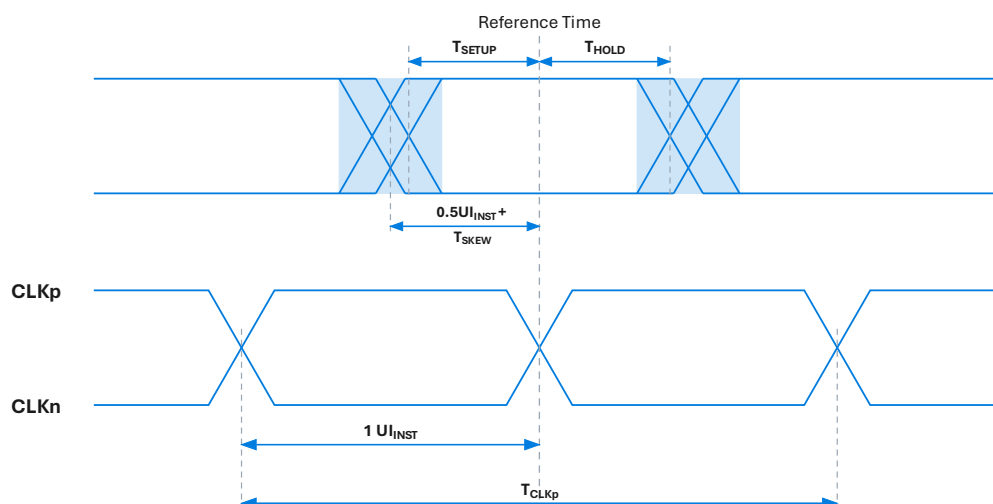


Timing of high-speed data transmission in bursts

10.6 MIPI Data-Clock Timing Specification

Parameter	Symbol	Min.	Typ.	Max.	Units
Data to clock setup time	$T_{\text{SETUP[RX]}}$	0.15 ⁽¹⁾	-	-	UI_{INST}
Data to clock hold time	$T_{\text{HOLD[RX]}}$	0.15 ⁽¹⁾	-	-	UI_{INST}

Note: (1) Total setup and hold window for receiver of $0.3 \cdot UI_{\text{INST}}$.



11. Quality Assurance

11.1 Purpose

This Quality Assurance standard ensures the quality of LCD module products supplied to the customer.

11.2 Standard for Quality Test

11.2.1 Sampling Plan:

GB/T2828.1-2012

Single sampling, general inspection level II

11.2.2 Sampling Criteria:

Visual inspection: AQL 1.5

Electrical functional: AQL 0.65.

11.2.3 Reliability Test:

For detailed requirements refer to Section 12 Reliability Specification.

11.3 Agreement Items

The following situations shall be negotiated with the customer:

11.3.1 Any discrepancy in the standard of quality assurance.

11.3.2 Additional requirements to be added to the product specification.

11.3.3 Any other special problem.

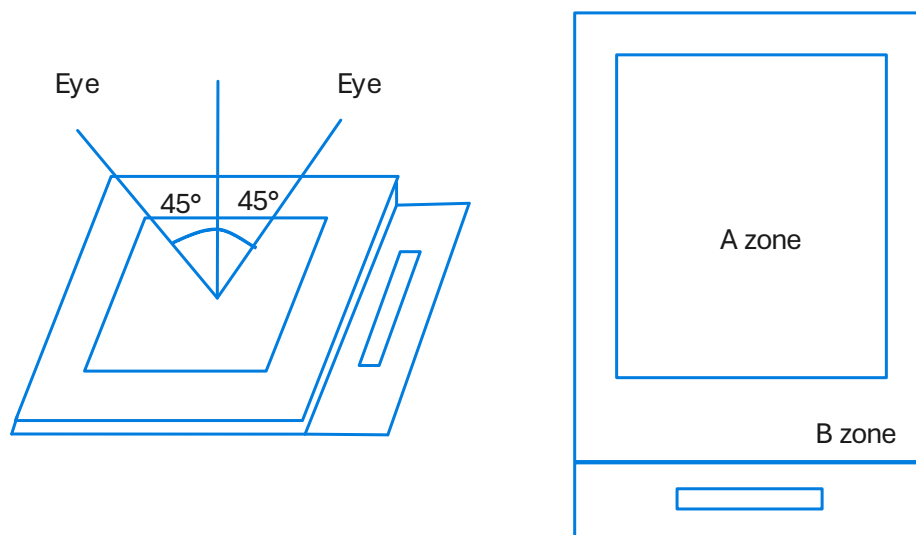
11.4 Standard of the Product Visual Inspection

11.4.1 Appearance inspection:

11.4.1.1 The inspection must be carried out under an illumination of about 1000 – 1500 lx, and the viewing distance must be 30 cm ± 2 cm.

11.4.1.2 The viewing angle should be 45° from the vertical line without reflected light, or follow the customer's viewing angle specifications.

11.4.1.3 Definition of area: A Zone: Active Area, B Zone: Viewing Area.

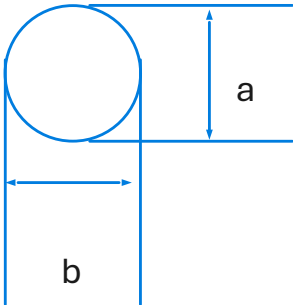


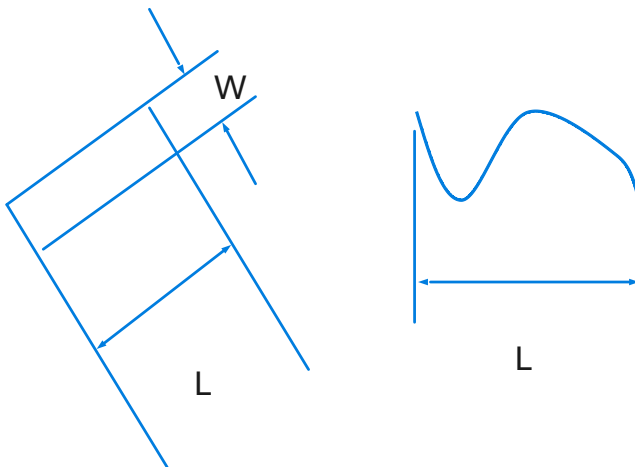
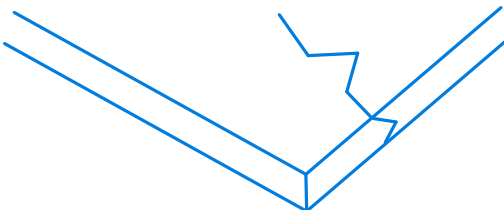
11.4.2 Basic principle:

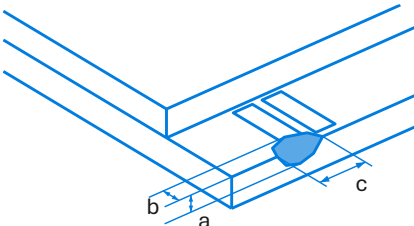
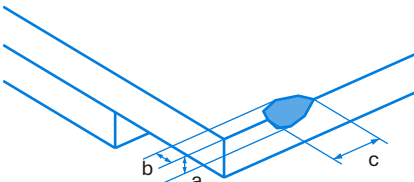
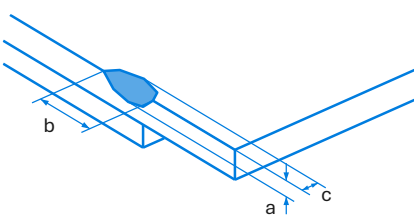
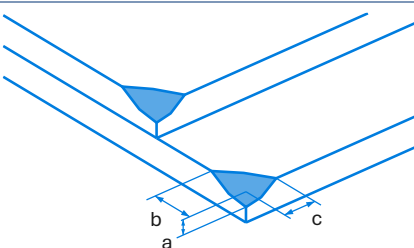
11.4.2.1 A set of samples to indicate the limit of acceptable quality level must be discussed by both us and the customer when a dispute occurs.

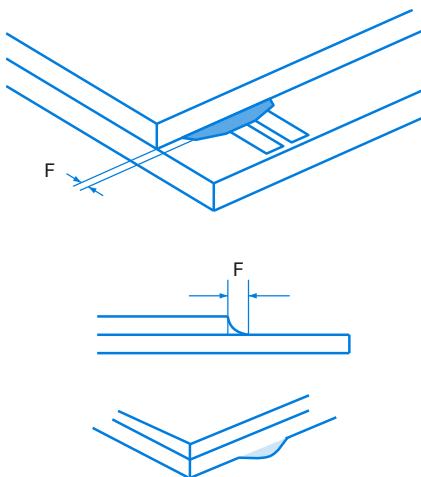
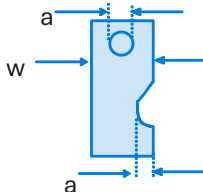
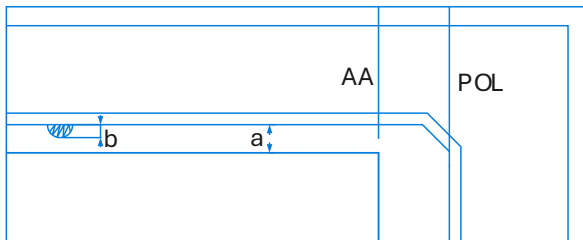
11.4.2.2 New items must be added when necessary.

11.5 Inspection Specification

No.	Item	Criteria (Unit: mm)									
01	Black / White spot Foreign material (Round type) Pinholes Stain Particles inside cell. (Minor defect)		<table><tr><th>Size \ Area</th><th>Acc. Qty</th></tr><tr><td>$\phi \leq 0.20$</td><td>Ignore</td></tr><tr><td>$0.20 < \phi \leq 0.50$</td><td>$N \leq 3$</td></tr><tr><td>$0.50 < \phi$</td><td>0</td></tr></table>	Size \ Area	Acc. Qty	$\phi \leq 0.20$	Ignore	$0.20 < \phi \leq 0.50$	$N \leq 3$	$0.50 < \phi$	0
			Size \ Area	Acc. Qty							
			$\phi \leq 0.20$	Ignore							
			$0.20 < \phi \leq 0.50$	$N \leq 3$							
			$0.50 < \phi$	0							
$\phi = (a + b) / 2$											
The distance between 2 defects should be more than 5 mm.											

No.	Item	Criteria (Unit: mm)				
02	Electrical Defect (Major defect)	Bright dot	Display Area	Total	Note 1	
			$N \leq 2$	$N \leq 2$		
		Dark dot	$N \leq 4$	$N \leq 4$		
		Total dot	$N \leq 4$	$N \leq 4$		
		Mura	Not visible through 5% ND filters.		Note 2	
Remark: 1. A bright dot caused by a scratch or a foreign object is judged according to item 01.						
03	Black and White line Scratch Foreign material (Line type) (Minor defect)					
		Length	Width	Acc. Qty		
		/	$W \leq 0.1$	Ignore		
		$L \leq 2.5$	$0.1 < W \leq 0.2$	3		
		$L > 2.5$	$0.2 < W$	0		
Total		3				
The distance between 2 defects should be more than 3 mm. Scratches not viewable through the back of the display are acceptable.						
04	Glass Crack (Major defect)	 Cracks of any type are not allowed, as a crack may enlarge.				

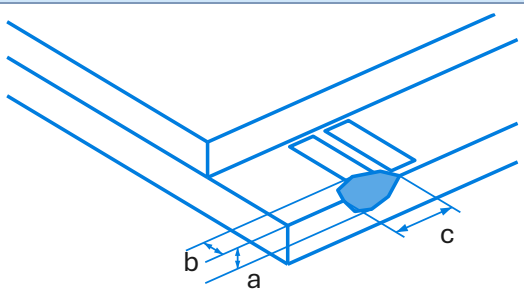
No.	Item	Criteria (Unit: mm)										
05	Glass Chipping Pad Area: (Minor defect)	 <table><tr><th>Length and Width</th><th>Acc. Qty</th></tr><tr><td>$c > 3.0, b < 1.0$</td><td>1</td></tr><tr><td>$c < 3.0, b < 1.0$</td><td>3</td></tr><tr><td colspan="2">$a < \text{Glass Thickness}$</td></tr></table>	Length and Width	Acc. Qty	$c > 3.0, b < 1.0$	1	$c < 3.0, b < 1.0$	3	$a < \text{Glass Thickness}$			
Length and Width	Acc. Qty											
$c > 3.0, b < 1.0$	1											
$c < 3.0, b < 1.0$	3											
$a < \text{Glass Thickness}$												
06	Glass Chipping Rear of Pad Area: (Minor defect)	 <table><tr><th>Length and Width</th><th>Acc. Qty</th></tr><tr><td>$c > 3.0, b < 1.0$</td><td>1</td></tr><tr><td>$c < 3.0, b < 1.0$</td><td>2</td></tr><tr><td>$c < 3.0, b < 0.5$</td><td>4</td></tr><tr><td colspan="2">$a < \text{Glass Thickness}$</td></tr></table>	Length and Width	Acc. Qty	$c > 3.0, b < 1.0$	1	$c < 3.0, b < 1.0$	2	$c < 3.0, b < 0.5$	4	$a < \text{Glass Thickness}$	
Length and Width	Acc. Qty											
$c > 3.0, b < 1.0$	1											
$c < 3.0, b < 1.0$	2											
$c < 3.0, b < 0.5$	4											
$a < \text{Glass Thickness}$												
07	Glass Chipping Except Pad Area: (Minor defect)	 <table><tr><th>Length and Width</th><th>Acc. Qty</th></tr><tr><td>$c > 3.0, b < 1.0$</td><td>1</td></tr><tr><td>$c < 3.0, b < 1.0$</td><td>2</td></tr><tr><td>$c < 3.0, b < 0.5$</td><td>4</td></tr><tr><td colspan="2">$a < \text{Glass Thickness}$</td></tr></table>	Length and Width	Acc. Qty	$c > 3.0, b < 1.0$	1	$c < 3.0, b < 1.0$	2	$c < 3.0, b < 0.5$	4	$a < \text{Glass Thickness}$	
Length and Width	Acc. Qty											
$c > 3.0, b < 1.0$	1											
$c < 3.0, b < 1.0$	2											
$c < 3.0, b < 0.5$	4											
$a < \text{Glass Thickness}$												
08	Glass Corner Chipping: (Minor defect)	 <table><tr><th>Length and Width</th><th>Acc. Qty</th></tr><tr><td>$c < 3.0, b < 3.0$</td><td>Ignore</td></tr><tr><td colspan="2">$a < \text{Glass Thickness}$</td></tr></table>	Length and Width	Acc. Qty	$c < 3.0, b < 3.0$	Ignore	$a < \text{Glass Thickness}$					
Length and Width	Acc. Qty											
$c < 3.0, b < 3.0$	Ignore											
$a < \text{Glass Thickness}$												

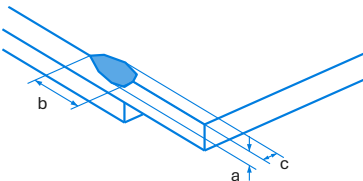
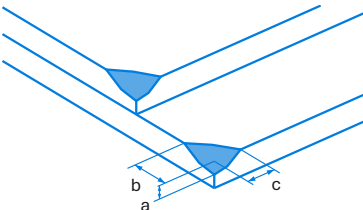
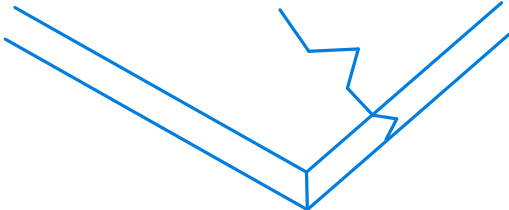
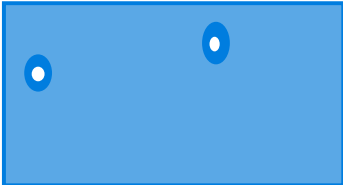
No.	Item	Criteria (Unit: mm)								
09	Glass Burr: (Minor defect)	 <table><thead><tr><th>Length</th><th>Acc. Qty</th></tr></thead><tbody><tr><td>$F < 1.0$</td><td>Ignore</td></tr></tbody></table> Glass burr must not affect assembly and module dimensions.	Length	Acc. Qty	$F < 1.0$	Ignore				
Length	Acc. Qty									
$F < 1.0$	Ignore									
10	FPC Defect: (Minor defect)	 10.1 Dent, pinhole width $a < w / 3$. (w: circuitry width.) 10.2 Open circuit is unacceptable. 10.3 No oxidation, contamination and distortion.								
11	Bubble on Polarizer (Minor defect)	<table><thead><tr><th>Diameter</th><th>Acc. Qty</th></tr></thead><tbody><tr><td>$\phi \leq 0.30$</td><td>Ignore</td></tr><tr><td>$0.30 < \phi \leq 0.50$</td><td>$N \leq 2$</td></tr><tr><td>$0.50 < \phi$</td><td>$N = 0$</td></tr></tbody></table>  $b < 1 / 2a$ Note: In high-temperature and high-humidity experiments, bubbles do not disperse.	Diameter	Acc. Qty	$\phi \leq 0.30$	Ignore	$0.30 < \phi \leq 0.50$	$N \leq 2$	$0.50 < \phi$	$N = 0$
Diameter	Acc. Qty									
$\phi \leq 0.30$	Ignore									
$0.30 < \phi \leq 0.50$	$N \leq 2$									
$0.50 < \phi$	$N = 0$									

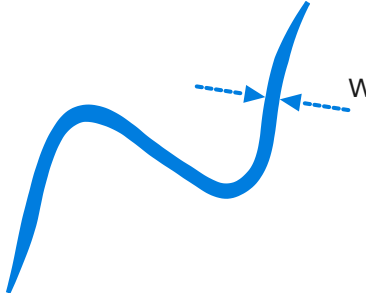
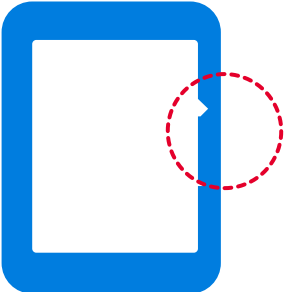
No.	Item	Criteria (Unit: mm)	
12	Dent on Polarizer (Minor defect)	Diameter	Acc. Qty
		$\phi \leq 0.25$	Ignore
		$0.25 < \phi \leq 0.50$	$N \leq 4$
		$0.50 < \phi$	None
13	Bezel	13.1 No rust or distortion on the bezel. 13.2 No visible fingerprints, stains or other contamination.	
14	PCB	14.1 No distortion or contamination on PCB terminals. 14.2 All components on the PCB must be the same as documented on the BOM / component layout. 14.3 Follow IPC-A-600F.	
15	Soldering	Follow the IPC-A-610C standard.	
16	Electrical Defect (Major defect)	The following defects must be rejected: 16.1 Missing vertical / horizontal line. 16.2 Abnormal Display. 16.3 No function or no display. 16.4 Current exceeds product specifications. 16.5 LCD viewing angle defect. 16.6 No Backlight. 16.7 Dark Backlight. 16.8 Touch panel not functioning.	

Remark: A broken LCD panel shall be rejected. Defects outside the LCD viewing area are acceptable.

Inspection Specification for the Capacitive Touch Panel

No.	Item	Criteria (Unit: mm)
01	Chipping Pad Area (cover lens not included): (Major defect)	 Chipping of any type is not allowed, as it seriously affects the product's function.

No.	Item	Criteria (Unit: mm)																						
02	Chipping Except Pad Area (cover lens not included): (Minor defect)	 <table><tr><th>Length and Width</th><th>Acc. Qty</th></tr><tr><td>$c < 1.5, b < 1$</td><td>$N \leq 5$</td></tr><tr><td colspan="2">$a < 1 / 2$ Glass Thickness</td></tr></table>	Length and Width	Acc. Qty	$c < 1.5, b < 1$	$N \leq 5$	$a < 1 / 2$ Glass Thickness																	
Length and Width	Acc. Qty																							
$c < 1.5, b < 1$	$N \leq 5$																							
$a < 1 / 2$ Glass Thickness																								
03	Corner Chipping (cover lens not included): (Minor defect)	 <table><tr><th>Length and Width</th><th>Acc. Qty</th></tr><tr><td>$c < 1.5, b < 0.5$</td><td>Ignore</td></tr><tr><td colspan="2">$a < 1 / 2$ Glass Thickness</td></tr></table>	Length and Width	Acc. Qty	$c < 1.5, b < 0.5$	Ignore	$a < 1 / 2$ Glass Thickness																	
Length and Width	Acc. Qty																							
$c < 1.5, b < 0.5$	Ignore																							
$a < 1 / 2$ Glass Thickness																								
04	Crack: (Minor defect)	 Cracks of any type are not allowed, as a crack may enlarge.																						
05	Cover lens must be without any chips, cracks or other damage when viewed from the front.																							
06	Same / Different color spot	 <table><tr><th colspan="2">D: diameter, W: width, L: length</th></tr><tr><th>Diameter</th><th>Acc. Qty</th></tr><tr><td>$D < 0.20$</td><td>Ignore</td></tr></table> Active Area: <table><tr><th>Diameter</th><th>Acc. Qty</th></tr><tr><td>$0.20 < D \leq 0.30$</td><td>2</td></tr><tr><td>$0.30 < D \leq 0.50$</td><td>1</td></tr><tr><td>$D > 0.5$</td><td>NG</td></tr></table> Viewing Area: <table><tr><th>Diameter</th><th>Acc. Qty</th></tr><tr><td>$D < 0.20$</td><td>Ignore</td></tr><tr><td>$0.20 < D \leq 0.5$</td><td>3</td></tr><tr><td>$D > 0.5$</td><td>NG</td></tr></table> The distance between 2 defects should be more than 15 mm.	D: diameter, W: width, L: length		Diameter	Acc. Qty	$D < 0.20$	Ignore	Diameter	Acc. Qty	$0.20 < D \leq 0.30$	2	$0.30 < D \leq 0.50$	1	$D > 0.5$	NG	Diameter	Acc. Qty	$D < 0.20$	Ignore	$0.20 < D \leq 0.5$	3	$D > 0.5$	NG
D: diameter, W: width, L: length																								
Diameter	Acc. Qty																							
$D < 0.20$	Ignore																							
Diameter	Acc. Qty																							
$0.20 < D \leq 0.30$	2																							
$0.30 < D \leq 0.50$	1																							
$D > 0.5$	NG																							
Diameter	Acc. Qty																							
$D < 0.20$	Ignore																							
$0.20 < D \leq 0.5$	3																							
$D > 0.5$	NG																							

No.	Item	Criteria (Unit: mm)		
07	Cover lens line scratch 			
		Length	Width	Acc. Qty
		/	$W \leq 0.08$	Ignore
		$L \leq 5$	$0.08 < W \leq 0.15$	2
		$L \leq 3$	$0.15 < W \leq 0.20$	1
		-	$W > 0.2$	NG
		$L > 5$	-	NG
The distance between 2 defects should be more than 15 mm.				
08	Printing sawtooth 			
		Length	Width	Acc. Qty
		/	$W \leq 0.2$	2
		$L \leq 2$	$0.2 < W \leq 0.3$	1
		$L \leq 2$	$W > 0.3$	NG

11.6 Classification of Defects

11.6.1 Visual defects (except missing / wrong label) are treated as minor defects, and electrical defects as major defects.

11.6.2 Two minor defects are equal to one major defect in lot sampling inspection.

11.7 Identification / Marking Criteria

Any unit with illegible, wrong, double or missing marking / label shall be rejected.

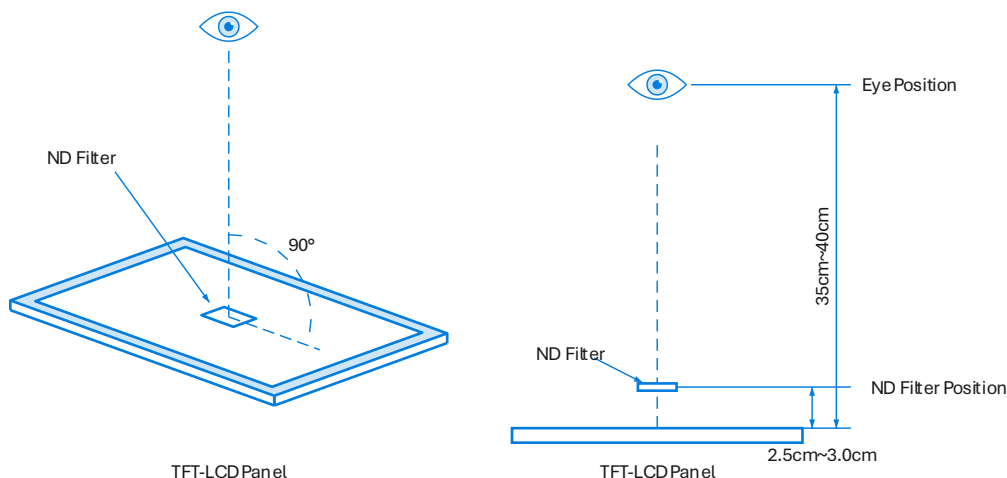
11.8 Packing

11.8.1 There should be no damage to the outer carton box; each packaging box should have one identical label.

11.8.2 Modules inside the package box should have a compliance mark.

11.8.3 All direct package materials shall offer ESD protection.

Note 1: Bright dot is defined as a dot whose defective area is larger than 50% of one sub-pixel area.



Bright dot: a dot-size bright defect on a black display pattern. It can be recognized through a 2% transmittance filter at an eye-to-panel distance of 350 mm $\pm$ 50 mm.

Dark dot: a cyan, magenta or yellow dot-size defect on a white display pattern. It can be recognized through a 5% transmittance filter at an eye-to-panel distance of 350 mm $\pm$ 50 mm.

Note 2: Mura — areas of the display that appear darker / brighter than the surrounding background.

12. Reliability Specification

No.	Item	Condition	Quantity	Criteria
1	High Temperature Operating	70°C, 96Hrs	2	GB/T2423.2-2008
2	Low Temperature Operating	-20°C, 96Hrs	2	GB/T2423.1-2008
3	High Humidity Storage	50°C, 90%RH, 96Hrs	2	GB/T2423.3-2016
4	High Temperature Storage	80°C, 96Hrs	2	GB/T2423.2-2008
5	Low Temperature Storage	-30°C, 96Hrs	2	GB/T2423.1-2008
6	Thermal Cycling Test Storage	-20°C, 60 min ~ 70°C, 60 min, 20 cycles.	2	GB/T2423.22-2012
7	Packing vibration	Frequency range: 10Hz ~ 50Hz Acceleration of gravity: 5G X, Y, Z: 30 min for each direction.	-	GB/T5170.14-2009
8	Electrostatic Discharge	Air: $\pm$ 4kV, 150pF / 330 Ω , 5 times Contact: $\pm$ 2kV, 150pF / 330 Ω , 5 times	2	GB/T17626.2-2018
9	Drop Test (Packaged)	Height: 80 cm, 1 corner, 3 edges, 6 surfaces.	-	GB/T2423.7-2018

Note 1: No cosmetic defects and no loss of operational function are allowed.

Note 2: The total current consumption should be below twice the initial value.

13. Precautions

13.1 Safety

13.1.1 The liquid crystal in the LCD is poisonous. Do not put it in your mouth. If the liquid crystal touches your skin or clothes, wash it off immediately using soap and water.

13.1.2 Since the liquid crystal cells are made of glass, do not subject them to strong impacts. Handle with care.

13.2 Handling

13.2.1 Store and use within ratings in order to keep performance and prevent damage.

13.2.2 Do not wipe the cover glass with a dry cloth, as it might cause scratches. If the surface of the cover glass needs to be cleaned, wipe it swiftly with cotton or another soft cloth soaked with IPA or petroleum benzine; do not use other chemicals.

13.3 Storage

13.3.1 Do not store the LCD module beyond the specified temperature ranges.

13.3.2 Strong light exposure causes degradation of the polarizer and color filter.

13.4 Operation

13.4.1 Response time will increase at lower temperatures.

13.4.2 The display may change color at different temperatures.

13.4.3 Mechanical disturbance during operation, such as pressing on the display area, may cause temporary display non-uniformity.

13.4.4 Do not connect or disconnect the LCM to or from the system when power is on.

13.4.5 Never use the LCM under abnormal conditions of high temperature and high humidity.

13.4.6 The module has high-frequency circuits. Sufficient suppression of electromagnetic interference shall be provided by the system manufacturer. Grounding and shielding methods may be important to minimize the interference.

13.4.7 Do not display a fixed pattern for a long time (we recommend no longer than one hour), as it may cause image sticking due to the TFT structure.

13.5 Static Electricity

13.5.1 This unit contains CMOS LSIs, so care must be taken to avoid electrostatic charge, e.g. by grounding the human body.

13.5.2 The normal static prevention measures should be observed for work clothes and benches.

13.5.3 The module should be kept in anti-static bags or other containers resistant to static for storage.

14. Legal Information

CE Marking

CE marking is obligatory only for complete end products. Unisystem display modules are semifinished goods designed to be integrated into finished devices and, therefore, are not CE marked.

Warranty

Unisystem grants a warranty for the proper operation of the goods for a period of 24 months from the date of delivery. If, as a result of a warranty claim, the customer receives a defect-free item as a replacement, the warranty period shall start anew from the moment the replacement is received.

Right to Change Specifications

Unisystem reserves the right to make changes to the product specifications, dimensions, and materials without prior notice in order to improve reliability, function, or design. It is the buyer's responsibility to verify that the datasheet is current before placing an order.

Intellectual Property

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High-Risk Applications Disclaimer

Unisystem products are not designed, intended, or authorized for use in safety-critical or high-risk applications where failure could directly result in personal injury, death, or severe environmental damage (e.g., life support machines, aerospace navigation, nuclear facilities). Using Unisystem products in such high-risk activities is entirely at the buyer's risk, and the buyer agrees to fully indemnify and hold Unisystem harmless from any damages or claims resulting from such unauthorized use.

15. Contact Information

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